



AF/IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

Brian Taggart et al.

Serial No.: 10/807,830

Filed: March 24, 2004

For: Lower Profile Flexible Substrate
Package for Electronic Components

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Art Unit: 2818

Examiner: Calvin Lee

Docket: ITL1119US
P18791

Assignee: Intel Corporation

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the final rejection mailed June 24, 2005, please amend the above-referenced patent application as follows:

OK TO ENTER
OK

Date of Deposit: July 6, 2005
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
Cynthia L. Hayden
Cynthia L. Hayden